Committing Committing Committed C	APPLICA	BLE STAN	NDARD									
Rating	Operating		\wedge	A 55.00 1 105.00(1)						-10°C to 6	:∩ °C	(2)
Power Contact : 30 A Quantility Range				Signal Contact : 50 V AC			orage Humidity Range			-10 0 10 0		
Current	Rating			Power Contact : 200 V AC						-	•	
ITEM		Current	I IOn				perating Humidity Range					
ITEM			•	SPEC	IFICA	TION	S					
CONSTRUCTION General Examination Visually and by measuring instrument. According to drawing. X X X X X X X X X	IT	EM						REC	QUIF	REMENTS	QT	АТ
Semeral Examination Visually and by measuring instrument. According to drawing. X X X						Į					1	1
ELECTRIC CHARACTERISTICS			Visually a	Visually and by measuring instrument.				ing to drav	wing.		×	×
Contact Resistance 100 mA(DC or 1000Hz) Signal Contact: 70m Q MAX Power Contact: 20m Q MAX P	Marking		Confirmed	• •								
Power Contact : 20m Q MAX	ELECTRIC CHARACT		TERISTICS									
Signal Contact : 100 V DC Power Contact : 100 M Ω MIN N	Contact Resi	istance	100 mA(E	OC or 1000Hz)			-				×	-
Power Contact : 250 V DC Power Contact : 1000 MΩ MIN. X X X X X X X X X	Insulation Res	sistance	Signal Co	Signal Contact : 100 V DC							×	+_
Voltage Proof Signal Contact: 150 V AC for 1 min. Power Contact: 600 V AC for 1 min. Power Contact: 600 V AC for 1 min. Power Contact: 600 V AC for 1 min. Vibration and Vibration Vibration Vibration Frequency 10 to 55 to 10Hz, approx 5min Signal contact: 80m Ω MAX. Power Contact: 30m Ω MAX. Power C		0.010.100					<u> </u>					
Power Contact : 600 V AC for 1 min.	Voltage Proo	of	Signal Co									
Insertion and Measured by applicable connector. Insertion Force: 18 N MAX. X - Withdrawal Forces 2 N Min. X - Withdrawal Force: 3 N Min.								No flashover or breakdown.				_
Withdrawal Forces												
Mechanical Operation 100 times insertions and extractions. 1			Measured	by applicable connector.						-	×	_
Signal Contact : 80m Ω MAX, Power Contact : 30m Ω MAX, Power Contact : 30m Ω MAX, Power Contact : 30m Ω MAX, 20m of Amage, crack and looseness of parts.			100 times	incertions and extractions							-	
Vibration Frequency 10 to 55 to 10Hz, approx 5min Single amplitude: 0.75 mm, 10 cycles for 3 axial directions. 2 No damage, crack and looseness of parts. 2 No damage, crack and looseness of pa	iviconanical Operation		100 times insertions and extractions.				Signal Contact : $80m \Omega$ MAX. Power Contact : $30m \Omega$ MAX.				×	_
For 3 axial directions	Vibration		Frequenc	y 10 to 55 to 10Hz, approx 5	min						×	_
A 3 times for 3 both axial directions.			Single am	Single amplitude: 0.75 mm, 10 cycles				· · · · · · · · · · · · · · · · · · ·				
ENVIRONMENTAL CHARACTERISTICS	Shock		490 m/s ² , duration of pulse 11 ms								×	-
Damp Heat (Steady state) Exposed at 40±2 °C, 90 ~ 95 %, 96 h. (Steady state) Contact Resistance: Signal Contact: 80m Ω MAX. X − Rapid Change of Temperature Time 30 → 30 min. under 5 cycles. (Relocation time to chamber: within 2~3 MiN) 20 Insulation Resistance: Signal Contact: 1000 MΩ MIN. No damage, crack and looseness of parts. Dry Heat	ENVIRON	MENTAL C				I					1	1
Signal Contact : 80m Ω MAX. Power Contact : 30m Ω MAX. X Temperature Time 30 → 30 min. Under 5 cycles. (Relocation time to chamber : within 2~3 MIN) 3 No damage, crack and looseness of parts. Signal Contact : 80m Ω MAX. X Temperature Time 30 → 30 min. 20 Insulation Resistance: Signal Contact : 1000 MΩ MIN. 3 No damage, crack and looseness of parts. Signal Contact : 80m Ω MAX. X Temperature Time 30 → 30 min. 20 Insulation Resistance: Signal Contact : 1000 MΩ MIN. 3 No damage, crack and looseness of parts. X Temperature Time 20					, 96 h.		① Cor	ntact Resis	stanc	e:	×	_
Time 100 → 30 → 30 min. under 5 cycles. (Relocation time to chamber: within 2~3 MIN) Cold Exposed at -55°C, 96 h Dry Heat			·									
under 5 cycles. (Relocation time to chamber : within 2~3 MIN) Power Contact : 1000 MΩ MIN. Power Contact : 1000 MΩ MIN. No damage, crack and looseness of parts. Cold Exposed at -55°C, 96 h Dry Heat Exposed at 105°C, 96 h Dry Heat Exposed at 105°C, 96 h Exposed at 105°C, 96 h Exposed at 25±2°C, 75±5%RH, 25 PPM for 96 h. (Test standard: IEC 68) Sulfur Dioxide Exposed at 25±2°C, 75±5%RH, 25 PPM for 96 h. (Test standard: IEC 68) To damage, crack and looseness of parts. Sulfur Dioxide Exposed at 25±2°C, 75±5%RH, 25 PPM for 96 h. (Test standard: IEC 68) To defect such as corrosion which impairs the function of connector. Contact Resistance: Signal Contact : 80m Ω MAX. Power Contact : 30m Ω MAX. Power Contact : 30m Ω MAX. Power Contact : 30m Ω MAX. Power Contact : 80m Ω Ω MAX. Power Contact : 80m Ω Ω MAX. Power		,	-	Temperature -55 → +85 °C							×	_
Relocation time to chamber : within 2~3 MIN) Power Contact : 1000 MΩ MIN.	Temperature)	_		nin.							
Contact Resistance: Signal Contact: 80m Ω MAX. Power Contact: 30m Ω							Power Contact : 1000 MΩ MIN.					
Exposed at 105°C, 96 h Power Contact: 30m Ω MAX. Ω No damage, crack and looseness of parts. Sulfur Dioxide Exposed at 25±2°C, 75±5%RH, 25 PPM for 96 h. (Test standard: IEC 68) Ω No defect such as corrosion which impairs the function of connector. ② Contact Resistance: Signal Contact: 80m Ω MAX. Power Contact: 30m Ω MAX.	Cold		Exposed a	Exposed at -55°C, 96 h			① Contact Resistance:				×	-
Sulfur Dioxide Exposed at 25±2°C, 75±5%RH, 25 PPM for 96 h. (Test standard: IEC 68) Test standard: IEC 68	Dry Heat		Exposed a	Exposed at 105°C, 96 h			Power Contact : 30m Ω MAX.				×	-
Test standard: IEC 68 the function of connector. (2) Contact Resistance: Signal Contact: 80m Ω MAX. Power Contact: 30m Ω MAX. Power Contact: 30m Ω MAX. Power Contact: 30m Ω MAX. Power Contact: 30m Ω MAX. Power Contact: 30m Ω MAX.	2=3		<u> </u>	. 05 . 0°0 . 75 . 50/DIL 05 5	2014 (0		- "				ļ.,	
Resistance to Soldering Heat 1)Reflow soldering: Peak TMP: 260°CMAX Reflow TMP: 220°CMIN for 60sec 2) Soldering irons: 360°C MAX. for 5 sec. Solderability Soldered at solder temperature 240±3°C for immersion duration, 3 sec. A new uniform coating of solder shall cover a minimum of 95 % of the surface being immersed. COUNT DESCRIPTION OF REVISIONS DESIGNED CHECKED DATE	Sullui Dioxide			l •			the function of connector. ② Contact Resistance: Signal Contact: 80m Ω MAX.				×	_
Soldering Heat Peak TMP: 260°CMAX Reflow TMP: 220°CMIN for 60sec 2) Soldering irons: 360°C MAX. for 5 sec. Solderability Soldered at solder temperature 240±3°C for immersion duration, 3 sec. COUNT DESCRIPTION OF REVISIONS DESIGNED CHECKED DATE 17. 02. 01 REMARKS (1) Include temperature rise caused by current-carrying. (2) "STORAGE" means a long-term storage state for the unused product before assembly to PCB. Unless otherwise specified, refer to IEC 60512. Note QT:Qualification Test A new uniform coating of solder shall cover a minimum of 95 % of the surface being immersed. A new uniform coating of solder shall cover a minimum of 95 % of the surface being immersed. A PROVED HT. YAMAGUCHI 17. 02. 01 CHECKED KN. SHIBUYA 14. 09. 02 DESIGNED TS. 00N0 14. 09. 02 DESIGNED TS. 00N0 TS. 00N0 TS. 00N0 TS. 00N0 TS. 00N0 TS. 00N0 TS. 00NO TS.	Resistance to		1)Reflow s	1)Reflow soldering :				1				 -
Soldered at solder temperature 240±3°C for immersion duration, 3 sec. COUNT DESCRIPTION OF REVISIONS DESIGNED CHECKED DATE 1. ONNO REMARKS (1) Include temperature rise caused by current-carrying. (2) "STORAGE" means a long-term storage state for the unused product before assembly to PCB. Unless otherwise specified, refer to IEC 60512. Note QT:Qualification Test AT:Assurance Test X:Applicable Test Soldered at solder temperature at a solder temperature at solder temperature aminimum of 95 % of the surface being immersed. A new uniform coating of solder shall cover a minimum of 95 % of the surface being immersed. A new uniform coating of solder shall cover a minimum of 95 % of the surface being immersed. A new uniform coating of solder shall cover a minimum of 95 % of the surface being immersed. A new uniform coating of solder shall cover a minimum of 95 % of the surface being immersed. A new uniform coating of solder shall cover a minimum of 95 % of the surface being immersed. A new uniform coating of solder shall cover a minimum of 95 % of the surface being immersed. A new uniform coating of solder shall cover a minimum of 95 % of the surface being immersed. A new uniform coating of solder shall cover a minimum of 95 % of the surface being immersed. A new uniform coating of solder shall cover a minimum of 95 % of the surface being immersed. A new uniform coating of solder shall cover a minimum of 95 % of the surface being immersed. A per of the surface being immersed.	Soldering Heat		Peak Ti Reflow	Peak TMP : 260°CMAX Reflow TMP: 220°CMIN for 60sec			looseness of the terminal.					
COUNT DESCRIPTION OF REVISIONS DESIGNED CHECKED DATE	Coldorol: !!!			-	sec.		Λ κα	uniform	004:	of colder shall server -	<u> </u>	1
COUNT DESCRIPTION OF REVISIONS DESIGNED CHECKED DATE 2 DIS-F-00002058 TS. 00N0 HT. YAMAGUCHI 17. 02. 01 REMARKS (1) Include temperature rise caused by current-carrying. (2) "STORAGE" means a long-term storage state for the unused product before assembly to PCB. Unless otherwise specified, refer to IEC 60512. Note QT:Qualification Test AT:Assurance Test X:Applicable Test DRAWING NO. SPECIFICATION SHEET PART NO. DESIGNED TS. 00N0 14. 09. 02 DRAWING NO. ELC-353566-00-00 FX23-40S-0. 5SH	Solderability						minimum of 95 % of the surface being				×	_
17. 02. 01 17. 02. 02 17. 02. 02 17. 02. 02 17. 02. 02 17. 02. 02 17. 02. 02 17. 02. 02 17. 02. 02 17. 02. 02 17. 02. 02 17. 02. 02 17. 02. 02 17. 02. 02 17. 02. 02 17. 02. 02 17. 02. 02 17. 02. 02. 02. 02. 02. 02. 02. 02. 02. 02	COUNT		ESCRIPTION OF REVISIONS DESIGNATION				<u> </u>					TF
REMARKS (1) Include temperature rise caused by current-carrying. (2) "STORAGE" means a long-term storage state for the unused product before assembly to PCB. Unless otherwise specified, refer to IEC 60512. Note QT:Qualification Test AT:Assurance Test X:Applicable Test SPECIFICATION SHEET PART NO. APPROVED HS. 0KAWA 14. 09. 02 CHECKED KN. SHIBUYA 14. 09. 02 DESIGNED TS. 00N0 14. 09. 02 DRAWN TS. 00N0 14. 09. 02 DRAWING NO. ELC-353566-00-00 FX23-40S-0. 5SH												
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Unless otherwise specified, refer to IEC 60512. Note QT:Qualification Test AT:Assurance Test X:Applicable Test DRAWING NO. SPECIFICATION SHEET PART NO. DRAWN TS. 00N0 14. 09. 02 DRAWING NO. ELC-353566-00-00 FX23-40S-0. 5SH		before assemb	oly to PCB.									
Note QT:Qualification Test AT:Assurance Test X:Applicable Test DRAWING NO. ELC-353566-00-00 SPECIFICATION SHEET PART NO. FX23-40S-0. 5SH	Unless oth	erwise spec	ified refer								14. 09. 02	
The Steel Pottion Sheet	·											
	ınc	S	SPECIFICATION SHEET			PART NC		NO. FX23-40		X23-40S-0. 5SH	5–0. 5SH	
HIROSE ELECTRIC CO., LTD. CODE NO. CL5/3-3402-1-00 <u>/2\</u> 1/1	CN	HIF	HIROSE ELECTRIC CO., LTD.				DE NO. CL573-3402-1-00 Z			2	1/1	